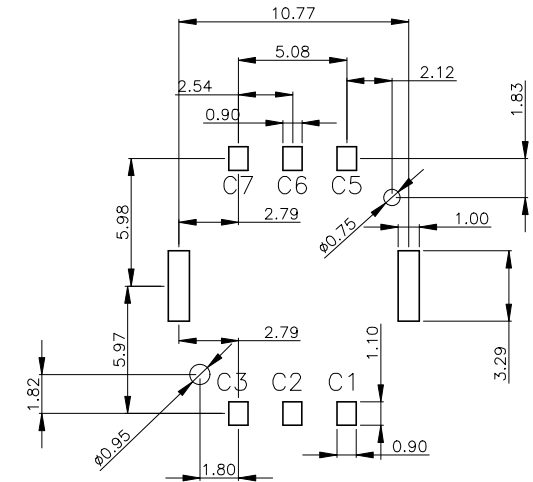
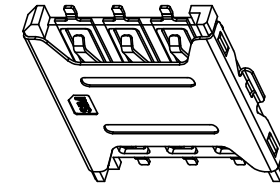
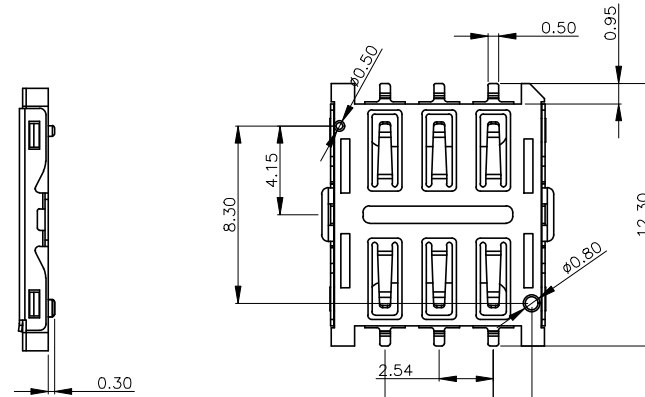
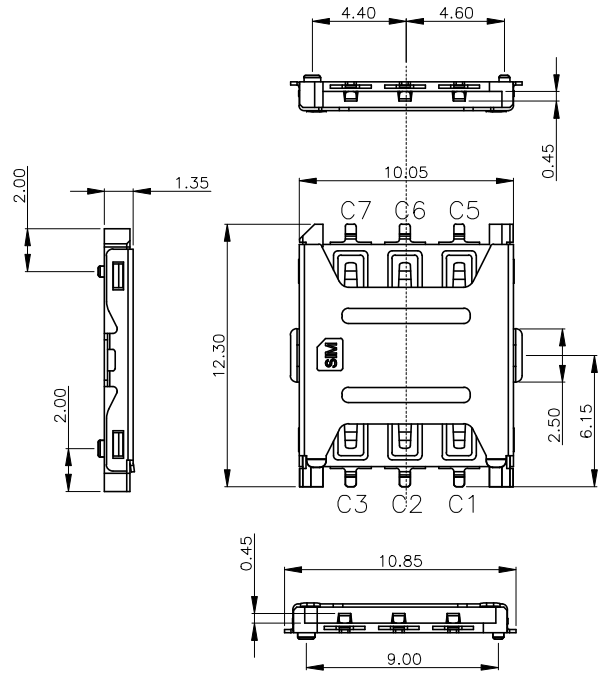
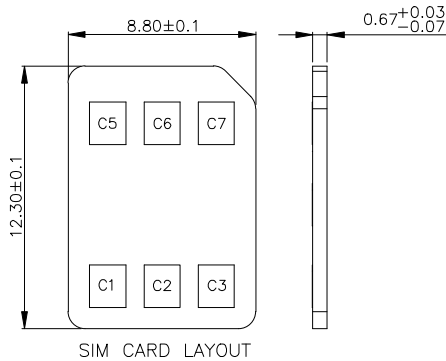




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)
RECOMMENDED METAL MASK T=0.12MM



SIM CARD LAYOUT

SPECIFICATION

MATERIAL:
 INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,UL 94V-0.
 CONTACT: C5210
 SHELL: SUS
PLATING:
 CONTACT: PLATED 50U" NI OVERALL CONTACT ALL AU 1U
 SHELL: PLATED 50U" NI OVERALL,PAD AU 1U
ELECTRICAL:
 CURRENT RATING: 0.5MA AC/DC MAX
 VOLTAGE RATING: 125V AC/DC
 AMBIENT TEMPERATURE RANGE: -20°C~+60°C
 STORAGE TEMPERATURE RANGE: -40°C~+70°C
 AMBIENT HUMIDITY RANGE: 95% R.H. MAX.
 CONTACT RESISTANCE: 100MΩMAX.
 INSULATION RESISTANCE: 1000MΩMIN./500VDC
 REFLOW PEAK TEMP: 260°C ±5°C, 3~5 S
 MATING CYCLES: 5,000 INSERTIONS MIN

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE	6Pin 1.35H PUSH PULL Nano SIM CARD CONN.		
X :±0.5	X :±2°	DWN	xiong	PART NO. SNO-1390	
X.X :±0.20	X.X :±1°	CHKD	lee	SCALE:1:1	UNIT: mm
X.XX :±0.10		APVD	wang	SIZE: A4	SHEET:10F 1
		REV: A4			
CUSTOMER COPY					